

10 9 8 7 6 5 4 3 2 1

F

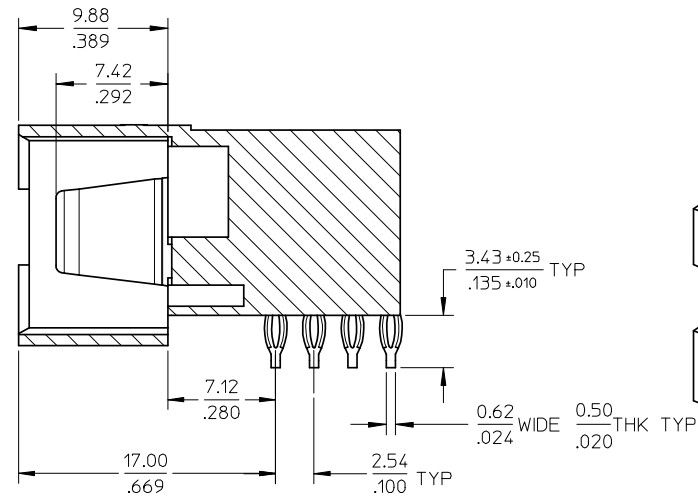
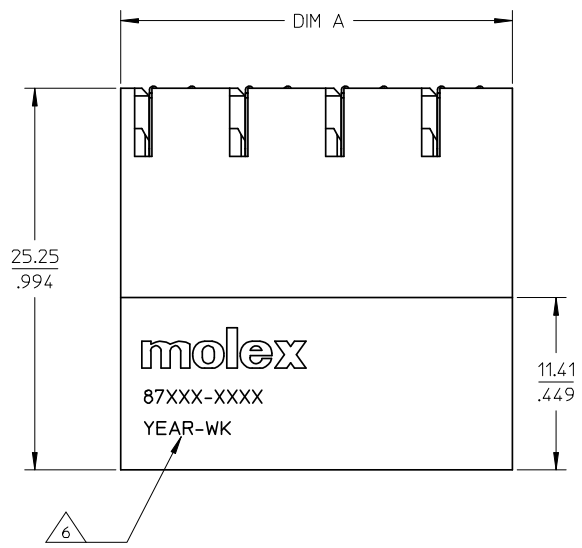
E

D

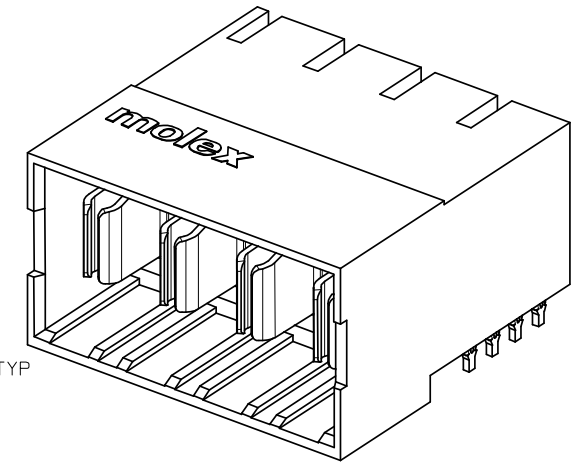
C

B

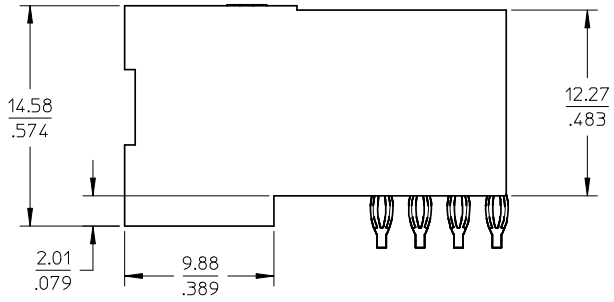
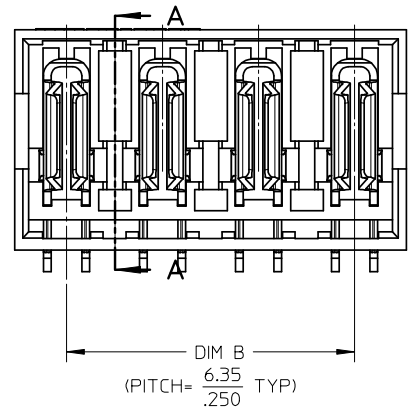
A



SECTION A-A



ISOMETRIC VIEW

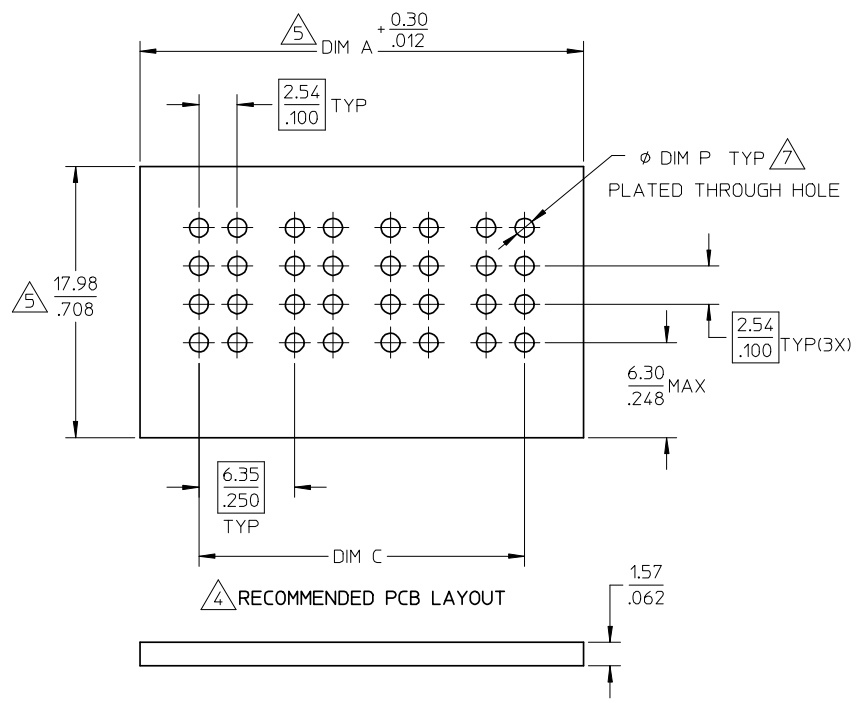


REVISED OSP HOLE SIZE EC NO: S2008-0551 DRWN:SKANG 2007/12/19 CHYK:ATSEE 2007/12/19 APPR:MLONG 2007/12/19	QUALITY SYMBOLS ▽=0 Ⓢ=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM/IN	NTS	METRIC		
D1	DESCRIPTION	4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 3 °		DRAWN BY: BHLW CHECKED BY: PTL IM APPROVED BY: SKTOH MATERIAL NO.: DATE: 2002/11/27 DATE: 2002/12/03 DATE: 2002/12/03	TITLE: HEADER, POWER CONN ALL BLADES POWER CONFIG. PRESS-FIT, R/A MOLEX INCORPORATED DOCUMENT NO.: SD-87682-011			SHEET NO.: 1 OF 2
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1

10	9	8	7	6	5	4	3	2	1
PART NUMBER	NO OF POWER PINS	DIM A	DIM B	DIM C	PACKAGING	PLATING OPTION (SOLDERTAIL)			
87682-0001	2	$\frac{13.20}{.520}$	$\frac{6.35}{.250}$	$\frac{8.89}{.350}$	TRAY	TIN/LEAD			
87682-0003	4	$\frac{25.90}{1.020}$	$\frac{19.05}{.750}$	$\frac{21.59}{.850}$	TRAY				
87682-2001	2	$\frac{13.20}{.520}$	$\frac{6.35}{.250}$	$\frac{8.89}{.350}$	TRAY	TIN			
87682-2003	4	$\frac{25.90}{1.020}$	$\frac{19.05}{.750}$	$\frac{21.59}{.850}$	TRAY				

	△ TYPE OF PCB	
	TIN/LEAD OR TIN	OSP
DRILLED HOLE SIZE	1.40mm/.055in	1.33mm/.052in
PLATING THICKNESS	0.007mm/.0003in MIN OVER 0.03mm/.001in TO 0.08mm/.003in COPPER	0.25µm/.001in MIN COPPER
PLATED HOLE SIZE △ (DIM P)	$\frac{1.25 \pm 0.08}{.049 \pm .003}$	$\frac{1.25 + 0.025 / - 0.050}{.049 + .001 / - .002}$



- NOTES:
- MATERIALS: HOUSING - HIGH TEMPERATURE, THERMO-PLASTIC  
GLASS FILLED, UL94V-0, COLOUR: BLACK  
POWER BLADES - COPPER ALLOY
  - FINISHES: POWER - SELECTIVE GOLD IN CONTACT AREA  
THICKNESS=0.76 µm /30 µm MINIMUM  
SELECTIVE TIN/LEAD OR TIN IN THE PC TAIL AREA  
THICKNESS= 2.54 µm /100 µm MINIMUM WITH  
1.27µm MINIMUM NICKEL UNDERPLATE OVERALL.
  - PRODUCT SPECIFICATION: PS-87680-006.  
APPLICATION SPECIFICATION: AS-87682-009.

- △ SEE SHEET 2 FOR RECOMMENDED PCB LAYOUT.
- △ COMPONENT STAY AWAY ZONE FROM CONNECTOR.
- △ MANUFACTURER LOGO, PART NUMBER AND YEAR-WK CODE.
- △ REFER TO RECOMMENDED PCB TABLE.

REVISED OSP HOLE SIZE EC NO: S2008-0551 DRWN:SKANG 2007/12/19 CHKD:ATSEE 2007/12/19 APPR:MLONG 2007/12/19	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		▽=0	mm	INCH	MM/IN		NTS	METRIC		
		∇=0	4 PLACES ± --- ± ---	3 PLACES ± --- ± .010	DRAWN BY	DATE	TITLE			
			2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	BHLOW	2002/11/27	HEADER, POWER CONN ALL BLADES POWER CONFIG. PRESS-FIT, R/A			
		ANGULAR ± 3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	MOLEX INCORPORATED			
					SKTOH	2002/12/03	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87682-011	SHEET NO. 2 OF 2
					SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			